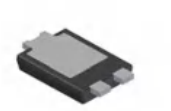
VOLTAGE RANGE
150 to 200 Volts
CURRENT
10.0Ampere

FEATURES

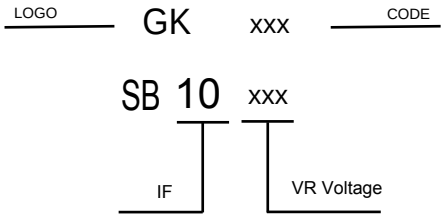
- Low forward voltage drop.
- Excellent high temperature stability.
- Fast switching capability.

MECHANICAL DATA



- Epoxy : UL94-V0 rated flame retardant.
- Case : Molded plastic, TO-277.
- Lead : Solder plated, solderable per MIL-STD-750, Method 2026.
- Polarity: Indicated by cathode band.
- Mounting Position : Any.
- Weight : Approximated 0.093 grams.





MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature uniess otherwies specified.
Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

TYPE NUMBER	SB10150	SB10200	UNITS
Maximum Recurrent Peak Reverse Voltage	150	200	V
Maximum RMS Voltage	105	140	V
Maximum DC Blocking Voltage	150	200	V
Maximum Average Forward Rectified Current See Fig. 1	10.0		A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	150		A
Maximum Instantaneous Forward Voltage at 10.0A	0.9		V
Maximum DC Reverse Current Ta=25°C	0.02		mA
at Rated DC Blocking Voltage Ta=100°C	2		mA
Typical Junction Capacitance (Note1)	570		pF
Typical Thermal Resistance R JA (Note 2)	60		°C/W
Operating Temperature Range T_J	-55 to +175		°C
Storage Temperature Range T_{STG}	-55 to +175		°C

Note : 1.FR-4 PCB, 2oz.Copper.
2.Polymide PCB, 2oz.Copper.Cathode pad dimensions 18.8mm x 14.4mm.Anode pad dimensions 5.6mm x 14.4mm.

RATING AND CHARACTERISTIC CURVES

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

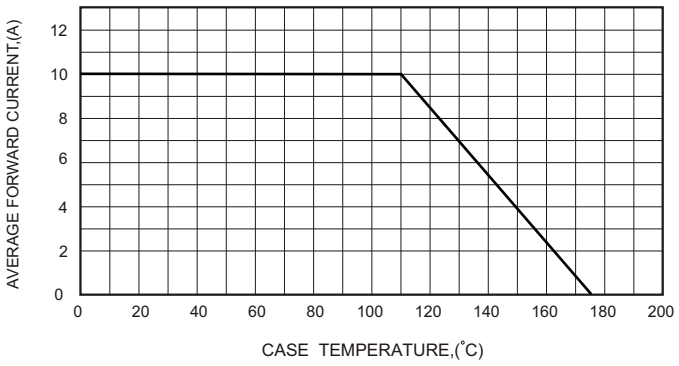


FIG.2-TYPICAL FORWARD CHARACTERISTICS

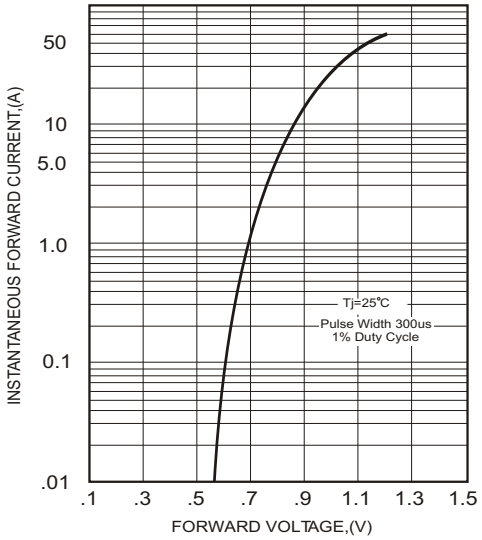


FIG.3 - TYPICAL REVERSE CHARACTERISTICS

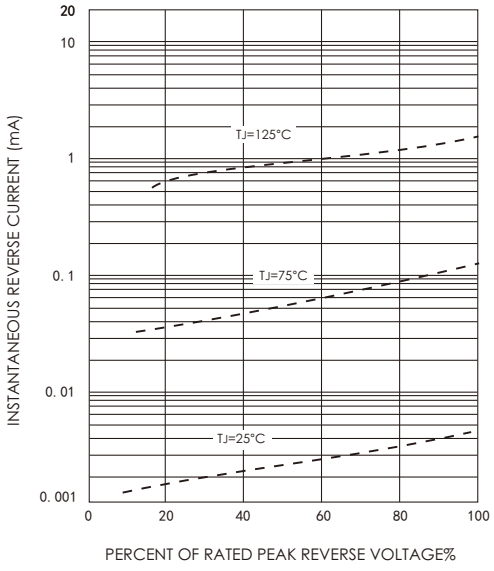


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

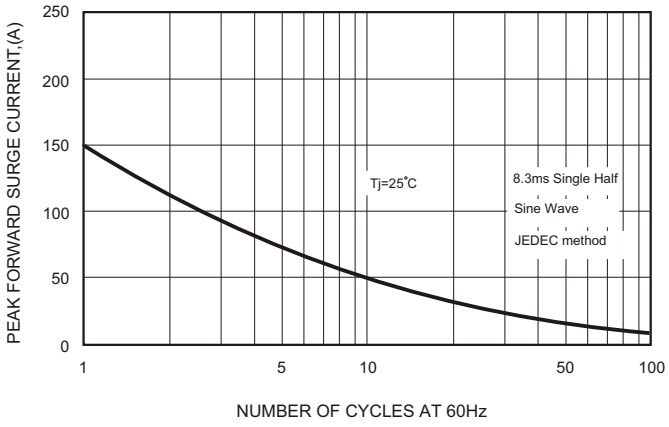
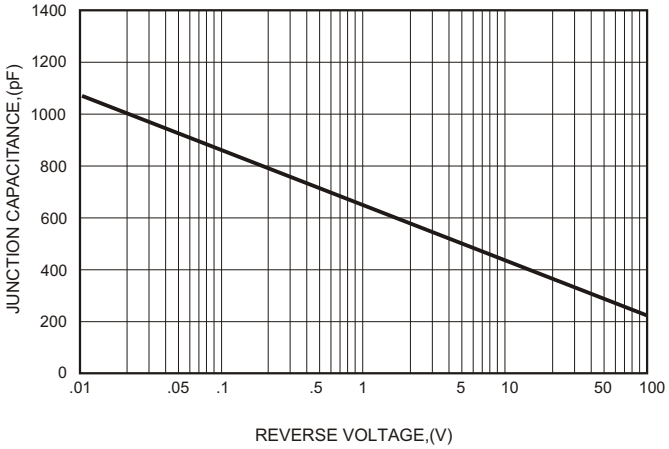


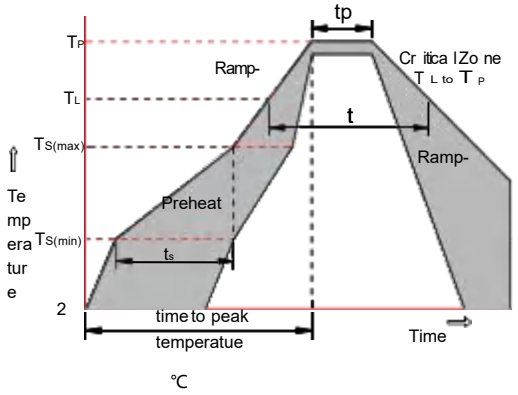
FIG.5-TYPICAL JUNCTION CAPACITANCE



Soldering parameters

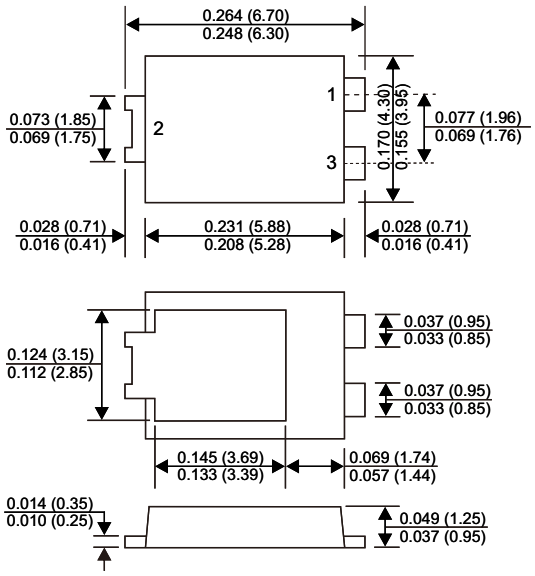
Reflow Condition		Pb-Free assembly (see as bellow)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150℃
	-Temperature Max($T_{s(max)}$)	+200℃
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3℃/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3℃/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217℃
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)℃
Time within 5℃ of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6℃/sec. Max
Time 25℃ to Peak Temp (T_P)		8 min. Max
Do not exceed		+260℃

FIG5: Reflow condition

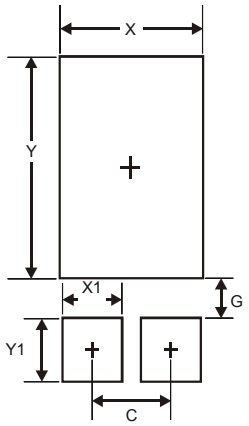


Package Dimensions & Suggested Pad Layout

TO - 277



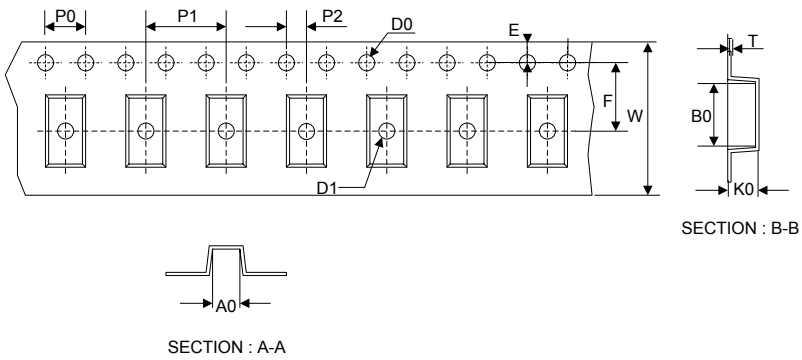
Dimensions in inches and (millimeters)



Dimensions	Value (in mm)
C	1.84
G	1.00
X	3.50
X1	1.40
Y	4.90
Y1	1.50

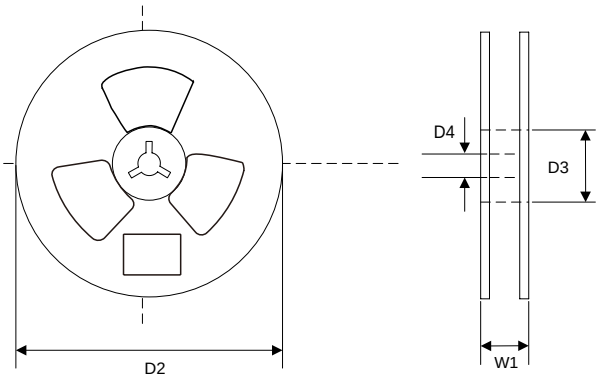
Tape & rell specification

Tape



Symbol	Dimension (mm)
P0	4.00±0.20
P1	8.00±0.20
P2	2.00±0.20
D0	1.55±0.20
D1	1.55±0.20
E	1.75±0.15
F	5.50±0.20
W	12.00±0.20
A0	4.50±0.20
B0	6.80±0.20
K0	1.35±0.20
T	0.23±0.10

13” Reel



D2	330.0±5.0
D3	73Min.
D4	13.5±2.5
W1	16.0±3.0
Quantity: 5000PCS	